



Click [here](#) for the 3D model.

| Dimensions |                 |
|------------|-----------------|
| L          | 1.6mm +/-0.2mm  |
| W          | 3.2mm +/-0.2mm  |
| T          | 0.8mm +/-0.10mm |
| P          | 0.8mm +/-0.10mm |

| Packaging Specifications |                        |
|--------------------------|------------------------|
| Packaging                | T&R, 180mm, Paper Tape |
| Packaging Quantity       | 4000                   |

| General Information      |  |
|--------------------------|--|
| Series                   | Array Comm X7R Flex                          |
| Style                    | SMD Array                                    |
| Description              | SMD, MLCC, Array, Flex Termination, Class II |
| RoHS                     | Yes  |
| Termination              | Flexible Termination                         |
| AEC-Q200                 | No   |
| Typical Component Weight | 23 mg  |
| Notes                    | Last Time Buy Date (LTB): May 30th, 2024.    |
| Chip Size                | 0612   |
| Shelf Life               | 78 Weeks                                     |
| MSL                      | 1  |

| Specifications   |   |
|--|---|
| Capacitance  | 1800 pF   |
| Measurement Condition  | 1 kHz 1.0Vrms                                   |
| Capacitance Tolerance  | 20%   |
| Voltage DC   | 10 VDC  |
| Dielectric Withstanding Voltage                                    | 25 VDC  |
| Temperature Range  | -55/+125°C                                      |
| Temperature Coefficient  | X7R   |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms                               |
| Dissipation Factor   | 5% 1 kHz 1.0Vrms                                |
| Aging Rate   | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance  | 100 GOhms                                       |